



Material Content Data Sheet



Sales Product Name		IKD15N60RF		Issued		1. August 2018		
MA#		MA001701938						
Package		PG-TO252-3-342		Weight*		333.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.995	0.60	0.60	5972	5972
leadframe	inorganic material	phosphorus	7723-14-0	0.048	0.01		144	
	non noble metal	iron	7439-89-6	0.160	0.05		480	
	non noble metal	copper	7440-50-8	160.096	47.92	47.98	479388	480012
	non noble metal	aluminium	7429-90-5	0.987	0.30	0.30	2955	2955
wire	non noble metal	aluminium	7429-90-5	0.987	0.30	0.30	2955	2955
encapsulation	organic material	carbon black	1333-86-4	1.161	0.35		3476	
	plastics	epoxy resin	-	16.250	4.87		48658	
	inorganic material	silicondioxide	60676-86-0	127.678	38.23	43.45	382316	434450
leadfinish	non noble metal	tin	7440-31-5	3.740	1.12	1.12	11199	11199
plating	non noble metal	nickel	7440-02-0	0.523	0.16	0.16	1567	1567
solder	non noble metal	tin	7440-31-5	0.042	0.01		127	
	noble metal	silver	7440-22-4	0.053	0.02		159	
	non noble metal	lead	7439-92-1	2.024	0.61	0.64	6059	6345
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		17	
	non noble metal	iron	7439-89-6	0.019	0.01		58	
	non noble metal	copper	7440-50-8	19.177	5.74	5.75	57425	57500
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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